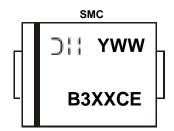


Marking Information (continued)



Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

Characteristic	Symbol	B350BE/B350CE	B360BE/B360CE	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	VRRM VRWM VRM	50	60	V
Average Rectified Output Current	lo	3		Α
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	IFSM	8	0	Α

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Ambient (Note 5) SMB	Dou	90	°C/W
SMC	Reja	70	C/VV
Typical Thermal Resistance Junction to Case (Note 5) SMB	Dava	50	°C/W
SMC	Rejc	30	C/VV
Operating and Storage Temperature Range	TJ, TSTG	-55 to +150	°C

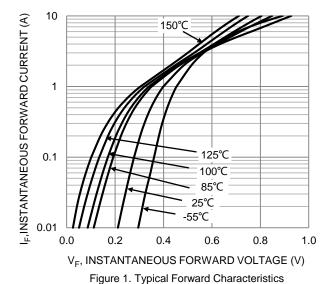
Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
	VF	_	0.55	0.65	V	IF = 3A, T _J = +25°C
Forward Voltage Drop		_	0.52	_		IF = 3A, TJ = +125°C
Leakage Current (Note 6) B350BE/ B350Cl	50CE	_	_	0.1		V _R = 50V, T _J = +25°C
B360BE/ B360CE	I_R		_	0.2	mA	$V_R = 60V, T_J = +25^{\circ}C$
		_	25	_		V _R = 60V, T _J = +125°C
Typical Capacitance	Ст	_	110	_	pF	V _R = 4.0V, f = 1MHz

Notes: 5. Device mounted on FR-4 substrate, 0.4"*0.5", 2oz, single-sided, PC boards with 0.2"*0.25" copper pad.

6. Short duration pulse test used to minimize self-heating effect.



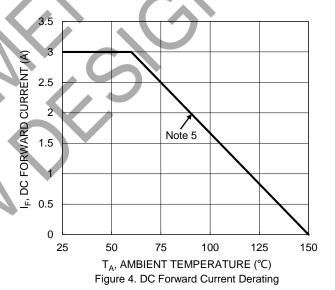


100 I_R, REVERSE LEAKAGE CURRENT (mA) 150°C 10 1 85°C 100°C 0.1 0.01 25°C 0.001 30 40 50 60 V_R, REVERSE VOLTAGE (V) Figure 2. Typical Reverse Characteristics

10000 (Ga) 1000 100 100 20 30 40 50 60

REVERSE VOLTAGE (V)

Figure 3. Typical Junction Capacitance

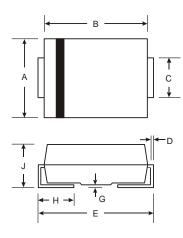




Package Outline Dimensions

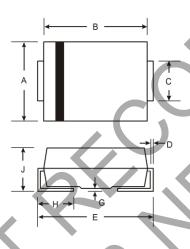
Please see http://www.diodes.com/package-outlines.html for the latest version.

SMB



SMB		
Dim	Min	Max
Α	3.30	3.94
В	4.06	4.57
C	1.96	2.21
D	0.15	0.31
Е	5.00	5.59
G	0.05	0.20
Н	0.76	1.52
J	2.00	2.50
All Dimensions in mm		

SMO



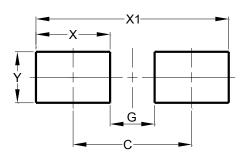
SMC		
Dim	Min	Max
A	5.59	6.22
В	6.60	7.11
C	2.75	3.18
D	0.15	0.31
Е	7.75	8.13
G	0.10	0.20
Н	0.76	1.52
J	2.00	2.50
All Dimensions in mm		



Suggested Pad Layout

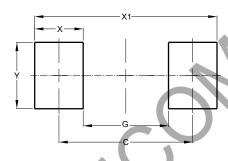
Please see http://www.diodes.com/package-outlines.html for the latest version.

SMB



Dimensions	Value (in mm)
С	4.30
G	1.80
Х	2.50
X1	6.80
Y	2.30

SMC



Dimensions	Value (in mm)	
Dimensions		
С	6.90	
G	4.40	
X	2.50	
X1	9.40	
Y	3.30	



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